

Celsee, Inc.

Genesis V2 Daughter PCB – PN 10000387 Rev. 2 03/29/2019

Fabrication Specification

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The following table identifies the fabrication specification for the PREP400 PCB:

Attribute	Specification
Board Size	10.24" x 5.67" (includes rails)
Layers	4
Stack Order	Top Signal (Component Side), Ground, Power, Bottom Signal
Material Type	FR4
Finished Thickness	0.62"
Rout Type	Individually routed
Array/Panel	The PCB already includes array rails. No additional arrays required.
Finished Plating	Lead-free solder
Copper Weight	1-oz
Drill	Specified in PTH and NPTH drill files.
Slots	No
Soldermask	Specified in top and bottom mask gerbers.
Soldermask Color	Blue
Silkscreen	Specified in top and bottom silk gerbers. No silk on pads.
Silkscreen Color	White
Gold Fingers	No
Dielectric Thickness	Use of standard dielectric stack as determined by design.
Impedance	No
RoHS	Yes
ITAR	No
Board Thickness Tolerance	+/- 10%
Dimensional Tolerance	+/- 10 mils
Inspection Criteria	IPC Class II